



SBOS177B - NOVEMBER 2000 - REVISED NOVEMBER 2004

Low-Noise, Low-Distortion INSTRUMENTATION AMPLIFIER

FEATURES

- LOW NOISE: 1nV/\Hz at 1kHz
- LOW THD+N: 0.002% at 1kHz, G = 100
- WIDE BANDWIDTH: 800kHz at G = 100
- WIDE SUPPLY RANGE: ±4.5V to ±18V
- HIGH CMR: > 100dB
- GAIN SET WITH EXTERNAL RESISTOR
- SO-14 SURFACE-MOUNT PACKAGE

APPLICATIONS

- PROFESSIONAL MICROPHONE PREAMPS
- MOVING-COIL TRANSDUCER AMPLIFIERS
- DIFFERENTIAL RECEIVERS
- BRIDGE TRANSDUCER AMPLIFIERS

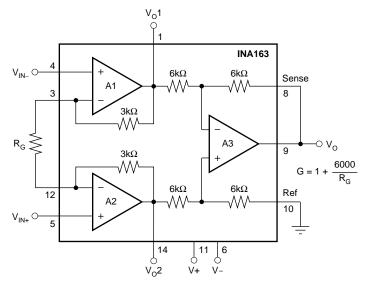
DESCRIPTION

The INA163 is a very low-noise, low-distortion, monolithic instrumentation amplifier. Its current-feedback circuitry achieves very wide bandwidth and excellent dynamic response over a wide range of gain. It is ideal for low-level audio signals such as balanced lowimpedance microphones. Many industrial, instrumentation, and medical applications also benefit from its low noise and wide bandwidth.

Unique distortion cancellation circuitry reduces distortion to extremely low levels, even in high gain. The INA163 provides near-theoretical noise performance for 200 Ω source impedance. Its differential input, low noise, and low distortion provide superior performance in professional microphone amplifier applications.

The INA163's wide supply voltage, excellent output voltage swing, and high output current drive allow its use in high-level audio stages as well.

The INA163 is available in a space-saving SO-14 surface-mount package, specified for operation over the -40° C to $+85^{\circ}$ C temperature range.



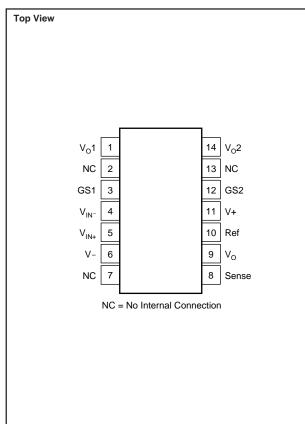


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PIN CONFIGURATION



ELECTROSTATIC DISCHARGE SENSITIVITY

This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

ABSOLUTE MAXIMUM RATINGS(1)

Power Supply Voltage	±18V
Signal Input Terminals, Voltage ⁽²⁾	
Current ⁽²⁾	10mA
Output Short-Circuit to Ground	Continuous
Operating Temperature	–55°C to +125°C
Storage Temperature	–55°C to +125°C
Junction Temperature	+150°C
Lead Temperature (soldering, 10s)	

NOTES: (1) Stresses above these ratings may cause permanent damage. Exposure to absolute maximum conditions for extended periods may degrade device reliability. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those specified is not implied. (2) Input terminals are diode-clamped to the power-supply rails. Input signals that can swing more than 0.5V beyond the supply rails should be current limited to 10mA or less.

PACKAGE/ORDERING INFORMATION⁽¹⁾

PRODUCT	PACKAGE-LEAD	PACKAGE DESIGNATOR	PACKAGE MARKING	ORDERING NUMBER ⁽²⁾	TRANSPORT MEDIA
INA163UA	SO-14 Surface Mount	D	INA163UA	INA163	Rails
"		"	"	INA163UA/2K5	Tape and Reel

NOTES: (1) For the most current package and ordering information, see the Package Option Addendum located at the end of this data sheet. (2) Models with a slash (/) are available only in Tape and Reel in the quantities indicated (e.g., /2K5 indicates 2500 devices per reel). Ordering 2500 pieces of "INA163UA/2K5" will get a single 2500-piece Tape and Reel.



ELECTRICAL CHARACTERISTICS: V_S = $\pm 15V$

 T_A = +25°C and at rated supplies, V_S = $\pm 15V,~R_L$ = 2k Ω connected to ground, unless otherwise noted.

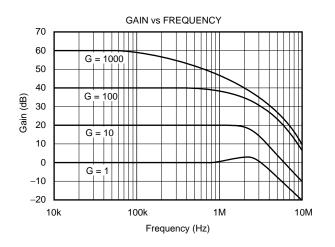
PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
GAIN					
Range			1 to 10000		V/V
Gain Equation ⁽¹⁾			$G = 1 + 6k/R_{G}$.,
•				+0.25	%
Gain Error, $G = 1$			±0.1	±0.25	
G = 10			±0.2	±0.7	%
G = 100			±0.2		%
G = 1000			±0.5		%
Gain Temp Drift Coefficient, G = 1			±1	±10	ppm/°C
G > 10			±25	±100	ppm/°C
Nonlinearity, $G = 1$			±0.0003		% of FS
G = 100			±0.0006		% of FS
			10.0000		// 0113
INPUT STAGE NOISE					
Voltage Noise	$R_{SOURCE} = 0\Omega$				
$f_0 = 1 \text{kHz}$			1		nV/√Hz
$f_{\Omega} = 100 Hz$			1.2		nV/√Hz
-					nV/√Hz
$f_0 = 10Hz$			2		IIV/VHZ
Current Noise					
$f_0 = 1 \text{kHz}$			0.8		pA/√Hz
OUTPUT STAGE NOISE					
Voltage Noise, $f_0 = 1 \text{ kHz}$			60		nV/√Hz
INPUT OFFSET VOLTAGE			1		
			E0 1 2000/C	250 + 5000/G	
Input Offset Voltage	$V_{CM} = V_{OUT} = 0V$		50 + 2000/G	250 + 5000/G	μV
vs Temperature	$T_A = T_{MIN}$ to T_{MAX}		1 + 20/G		μV/°C
vs Power Supply	$V_{S} = \pm 4.5 V$ to $\pm 18 V$		1 + 50/G	3 + 200/G	μV/V
INPUT VOLTAGE RANGE					
Common-Mode Voltage Range	$V_{IN+} - V_{IN-} = 0V$	(V+) − 4	(V+) − 3		V
Common Mode Voltage Range	$V_{IN+} - V_{IN-} = 0V$	(V-) + 4	(V-) + 3		v
Common Mada Deiratian C. 1	$v_{IN+} - v_{IN-} = 0.0$. ,			-
Common-Mode Rejection, $G = 1$	$V_{CM} = \pm 11V, R_{SRC} = 0\Omega$	70	80		dB
G = 100		100	116		dB
INPUT BIAS CURRENT					
Initial Bias Current			2	12	μA
			10		nA/°C
vs Temperature					
Initial Offset Current			0.1	1	μA
vs Temperature			0.5		nA/°C
INPUT IMPEDANCE					
	Differential		60 2		MΩ pF
	Common-Mode		60 2		MΩ pF
DYNAMIC RESPONSE					
Bandwidth, Small Signal, –3dB, G = 1			3.4		
G = 100			800		kHz
Slew Rate			15		V/µs
THD+Noise, f = 1kHz	G = 100		0.002		%
Settling Time, 0.1%	G = 100, 10V Step		2		μs
0.01%	G = 100, 10V Step		3.5		μs
Overload Recovery	50% Overdrive		1		μs μs
					μο
OUTPUT			()()) 10		
Voltage	$R_L = 2k\Omega$ to Gnd	(V+) − 2	(V+) - 1.8		V
		(V–) + 2	(V–) + 1.8		V
Load Capacitance Stability			1000		pF
Short-Circuit Current	Continuous-to-Common		±60		mA
POWER SUPPLY					
Rated Voltage			±15		V
			10		
Voltage Range		±4.5		±18	V
Current, Quiescent	$I_{O} = OmA$		±10	±12	mA
TEMPERATURE RANGE					
Specification		-40		+85	°C
Operating		-40		+125	°Č
θ_{JA}		UT 0	100		°C/W
			1 100	I I	~(:////

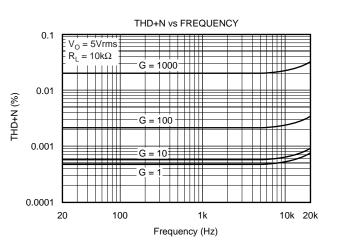
NOTE: (1) Gain accuracy is a function of external $\mathsf{R}_{\mathsf{G}}.$

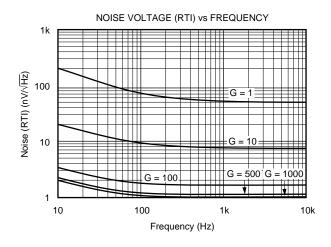


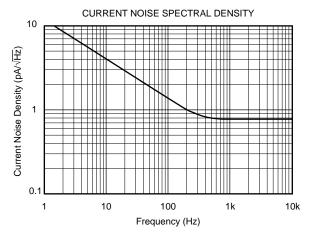
TYPICAL CHARACTERISTICS

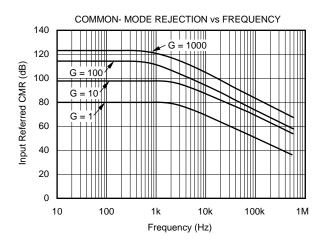
At T_A = +25°C, V_S = 5V, V_{CM} = 1/2V_S, R_L = 25k\Omega, CL = 50pF, unless otherwise noted.

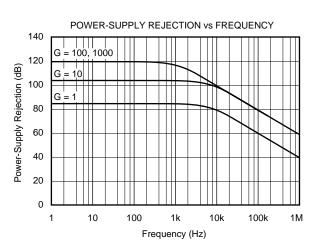






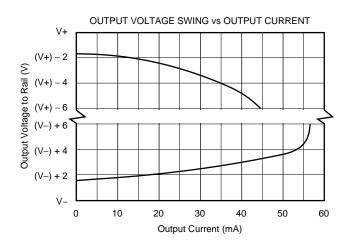


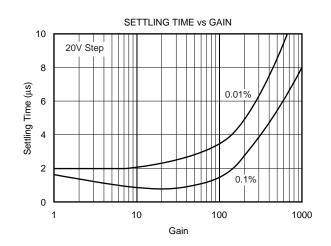


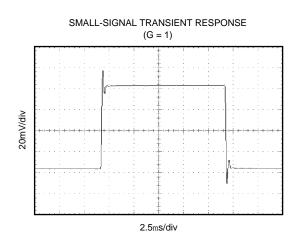


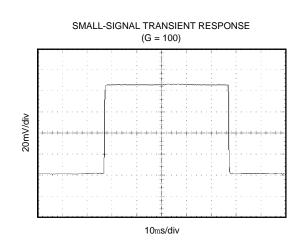
TYPICAL CHARACTERISTICS (Cont.)

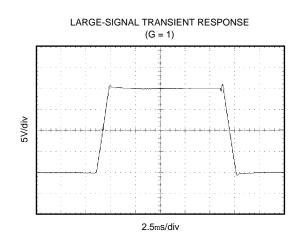
At T_A = +25°C, V_S = 5V, V_{CM} = 1/2V_S, R_L = 25k\Omega, CL = 50pF, unless otherwise noted.

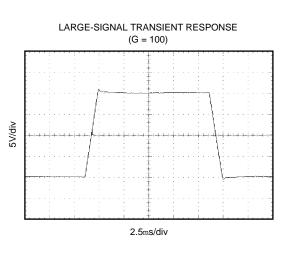
















APPLICATIONS INFORMATION

Figure 1 shows the basic connections required for operation. Power supplies should be bypassed with 0.1μ F tantalum capacitors near the device pins. The output Sense (pin 8) and output Reference (pin 10) should be low-impedance connections. Resistance of a few ohms in series with these connections will degrade the common-mode rejection of the INA163.

GAIN-SET RESISTOR

Gain is set with an external resistor, R_G, as shown in Figure 1. The two internal $3k\Omega$ feedback resistors are laser-trimmed to $3k\Omega$ within approximately ±0.2%. Gain is:

$$G = 1 + \frac{6000}{R_G}$$

The temperature coefficient of the internal $3k\Omega$ resistors is approximately ± 25 ppm/°C. Accuracy and TCR of the external R_G will also contribute to gain error and

temperature drift. These effects can be inferred from the gain equation. Make a short, direct connection to the gain set resistor, R_G . Avoid running output signals near these sensitive input nodes.

NOISE PERFORMANCE

The INA163 provides very low-noise with low-source impedance. Its $1nV/\sqrt{Hz}$ voltage noise delivers near-theoretical noise performance with a source impedance of 200 Ω . The input stage design used to achieve this low noise, results in relatively high input bias current and input bias current noise. As a result, the INA163 may not provide the best noise performance with a source impedance greater than $10k\Omega$. For source impedance greater than $10k\Omega$, other instrumentation amplifiers may provide improved noise performance.

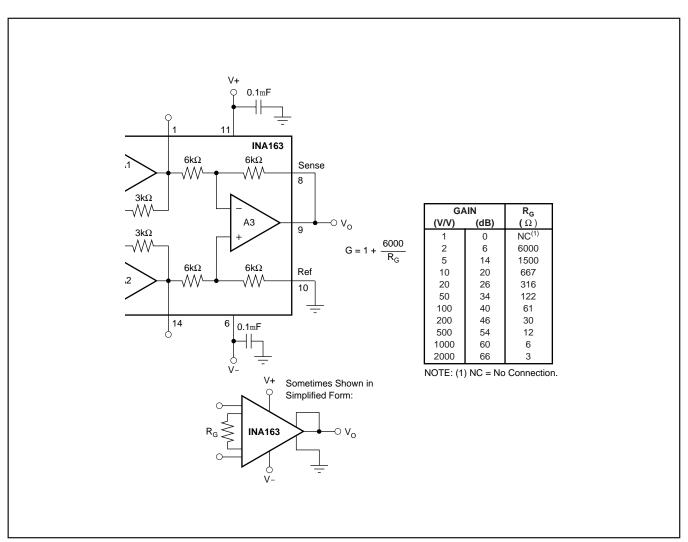


FIGURE 1. Basic Circuit Connections.

INPUT CONSIDERATIONS

Very low source impedance (less than 10Ω) can cause the INA163 to oscillate. This depends on circuit layout, signal source, and input cable characteristics. An input network consisting of a small inductor and resistor, as shown in Figure 2, can greatly reduce any tendency to oscillate. This is especially useful if a variety of input sources are to be connected to the INA163. Although not shown in other figures, this network can be used as needed with all applications shown.

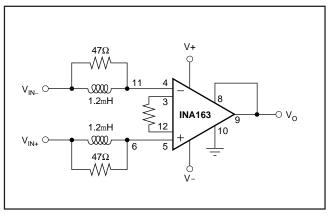


FIGURE 2. Input Stabilization Network.

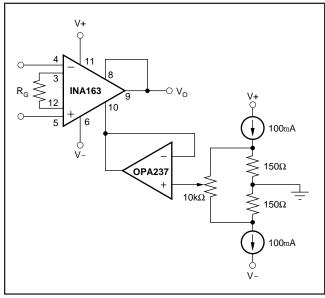


FIGURE 3. Offset Voltage Adjustment Circuit.

OFFSET VOLTAGE TRIM

A variable voltage applied to pin 10, as shown in Figure 3, can be used to adjust the output offset voltage. A voltage applied to pin 10 is summed with the output signal. An op amp connected as a buffer is used to provide a low impedance at pin 10 to assure good common-mode rejection.

OUTPUT SENSE

An output sense terminal allows greater gain accuracy in driving the load. By connecting the sense connection at the load, $I \cdot R$ voltage loss to the load is included inside the feedback loop. Current drive can be increased by connecting a buffer amp inside the feedback loop, as shown in Figure 4.

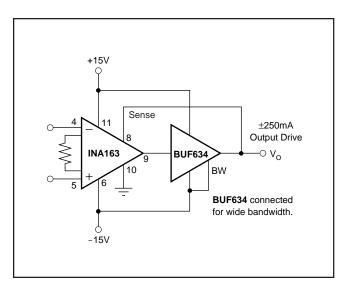


FIGURE 4. Buffer for Increase Output Current.



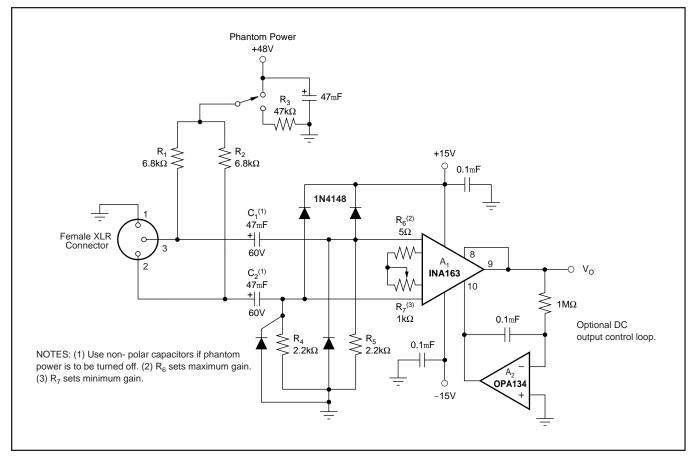


FIGURE 5. Phantom-Powered Microphone Preamplifier.

MICROPHONE AMPLIFIER

Figure 5 shows a typical circuit for a professional microphone input amplifier. R_1 and R_2 provide a current path for conventional 48V phantom power source for a remotely located microphone. An optional switch allows phantom power to be disabled. C_1 and C_2 block the phantom power voltage from the INA163 input circuitry. Non-polarized capacitors should be used for C_1 and C_2 if phantom power is to be disabled.

 R_4 and R_5 provide a path for input bias current of the INA163. Input offset current (typically 100nA) creates a DC differential input voltage that will produce an output offset voltage. This is generally the dominant source of

output offset voltage in this application. With a maximum gain of 1000 (60dB), the output offset voltage can be several volts. This may be entirely acceptable if the output is AC-coupled into the subsequent stage. An alternate technique is shown in Figure 5. An inexpensive FET-input op amp in a feedback loop drives the DC output voltage to 0V. A_2 is not in the audio signal path and does not affect signal quality.

Gain is set with a variable resistor, R_7 , in series with R_6 . R_6 determines the maximum gain. The total resistance, $R_6 + R_7$, determines the lowest gain. A special reverse-log taper potentiometer for R_7 can be used to create a linear change (in dB) with rotation.



PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
INA163UA	ACTIVE	SOIC	D	14	58	None	CU SNPB	Level-3-220C-168 HR
INA163UA/2K5	ACTIVE	SOIC	D	14	2500	None	CU SNPB	Level-3-220C-168 HR

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - May not be currently available - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

None: Not yet available Lead (Pb-Free).

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at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. Green (RoHS & no Sb/Br): TI defines "Green" to mean "Pb-Free" and in addition, uses package materials that do not contain halogens, including bromine (Br) or antimony (Sb) above 0.1% of total product weight.

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDECindustry standard classifications, and peak solder temperature.

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D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-012 variation AB.



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